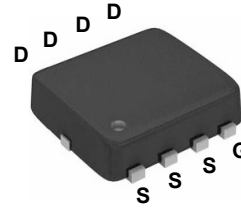
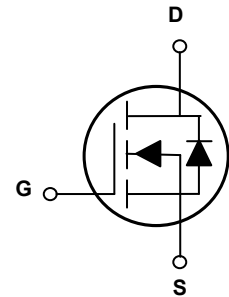


Main Product Characteristics

BV_{DSS}	30V
$R_{DS(ON)}$	7.2m Ω (Max.)
I_D	54A



PPAK 3x3



Schematic Diagram

Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



Description

The GSFN0354 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

Absolute Maximum Ratings ($T_C=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Drain Current-Continuous ($T_C=25^\circ\text{C}$)	I_D	54	A
Drain Current-Continuous ($T_C=100^\circ\text{C}$)		34	
Drain Current-Pulsed ¹	I_{DM}	216	A
Single Pulse Avalanche Energy ²	E_{AS}	45	mJ
Single Pulse Avalanche Current ²	I_{AS}	30	A
Power Dissipation ($T_C=25^\circ\text{C}$)	P_D	34.7	W
Power Dissipation-Derate above 25 $^\circ\text{C}$		0.28	
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	62	$^\circ\text{C}/\text{W}$
Thermal Resistance Junction to Case	$R_{\theta JC}$	3.6	$^\circ\text{C}/\text{W}$
Operating Junction Temperature Range	T_J	-55 To +150	$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-55 To +150	$^\circ\text{C}$

Electrical Characteristics (T_J=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
On/Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D =250μA	30	-	-	V
BV _{DSS} Temperature Coefficient	ΔBV _{DSS} /ΔT _J	Reference to 25°C, I _D =1mA	-	0.04	-	V/°C
Drain-Source Leakage Current	I _{DSS}	V _{DS} =30V, V _{GS} =0V, T _J =25°C	-	-	1	μA
		V _{DS} =24V, V _{GS} =0V, T _J =125°C	-	-	10	μA
Gate-Source Leakage Current	I _{GSS}	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Static Drain-Source On-Resistance ³	R _{DS(ON)}	V _{GS} =10V, I _D =16A	-	5.7	7.2	mΩ
		V _{GS} =4.5V, I _D =8A	-	8.4	11.5	
Gate Threshold Voltage	V _{GS(th)}	V _{GS} =V _{DS} , I _D =250μA	1.2	1.6	2.5	V
V _{GS(th)} Temperature Coefficient	ΔV _{GS(th)}		-	-4	-	mV/°C
Forward Transconductance	g _{fs}	V _{DS} =10V, I _D =3A	-	15	-	S
Dynamic and Switching Characteristics						
Total Gate Charge ^{3,4}	Q _g	V _{DS} =15V, I _D =20A, V _{GS} =10V	-	11.4	22	nC
Gate-Source Charge ^{3,4}	Q _{gs}		-	2.1	4	
Gate-Drain Charge ^{3,4}	Q _{gd}		-	2.5	5	
Turn-On Delay Time ^{3,4}	t _{d(on)}	V _{DD} =15V, R _G =3.3Ω, V _{GS} =10V, I _D =15A	-	4.8	9	nS
Rise Time ^{3,4}	t _r		-	12.5	24	
Turn-Off Delay Time ^{3,4}	t _{d(off)}		-	27.6	52	
Fall Time ^{3,4}	t _f		-	8.2	16	
Input Capacitance	C _{iss}	V _{DS} =25V, V _{GS} =0V, F=1MHz	-	850	1700	pF
Output Capacitance	C _{oss}		-	133	260	
Reverse Transfer Capacitance	C _{rss}		-	78	160	
Gate Resistance	R _g	V _{GS} =0V, V _{DS} =0V, F=1MHz	-	2.4	-	Ω
Guaranteed Avalanche Energy						
Single Pulse Avalanche Energy	E _{AS}	V _{DD} =25V, L=0.1mH, I _{AS} =15A	12	-	-	mJ
Drain-Source Diode Characteristics and Maximum Ratings						
Continuous Source Current	I _S	V _G =V _D =0V, Force Current	-	-	54	A
Pulsed Source Current ³	I _{SM}		-	-	108	A
Diode Forward Voltage ³	V _{SD}	V _{GS} =0V, I _S =1A, T _J =25°C	-	-	1	V
Reverse Recovery Time	T _{rr}	V _{GS} =0V, I _S =10A, di/dt=100A/μs, T _J =25°C	-	126	-	nS
Reverse Recovery Charge	Q _{rr}		-	165	-	nC

Notes:

1. Repetitive rating: Pulsed width limited by maximum junction temperature.
2. V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=30A, R_G=25Ω, starting T_J=25°C.
3. Pulse test: pulse width ≤ 300us, duty cycle ≤ 2%.
4. Essentially independent of operation temperature.

Typical Electrical and Thermal Characteristic Curves

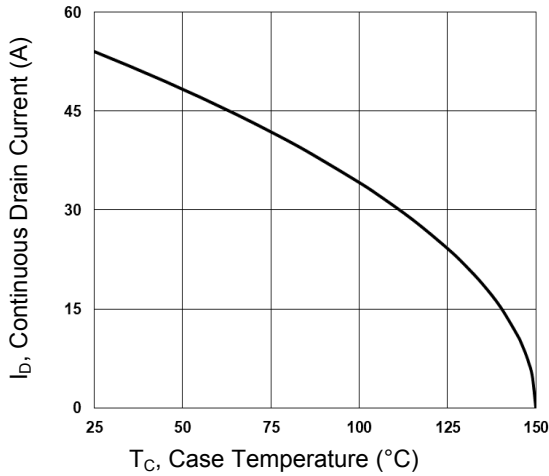


Figure 1. Continuous Drain Current vs. T_C

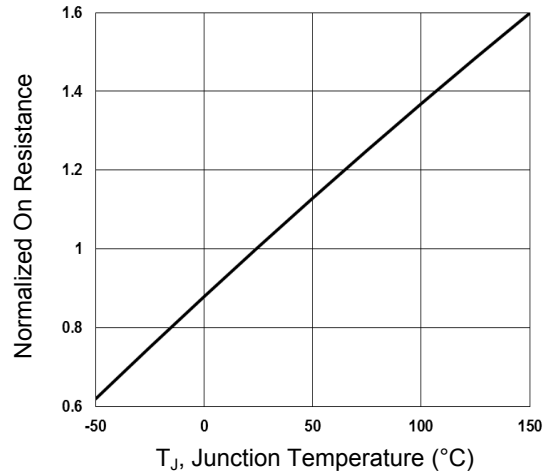


Figure 2. Normalized $R_{DS(on)}$ vs. T_J

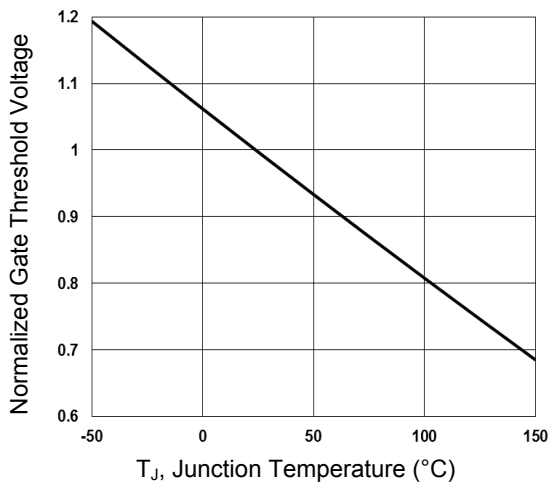


Figure 3. Normalized V_{th} vs. T_J

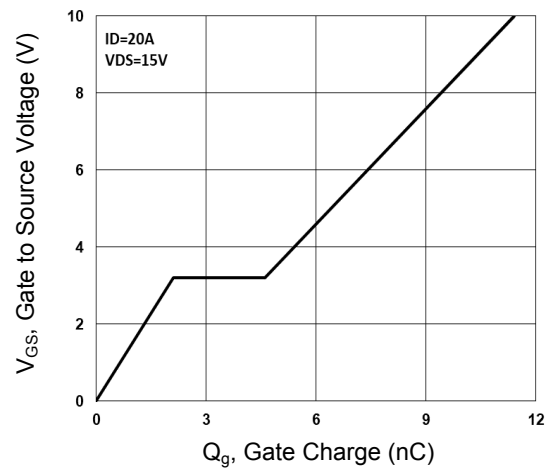


Figure 4. Gate Charge Waveform

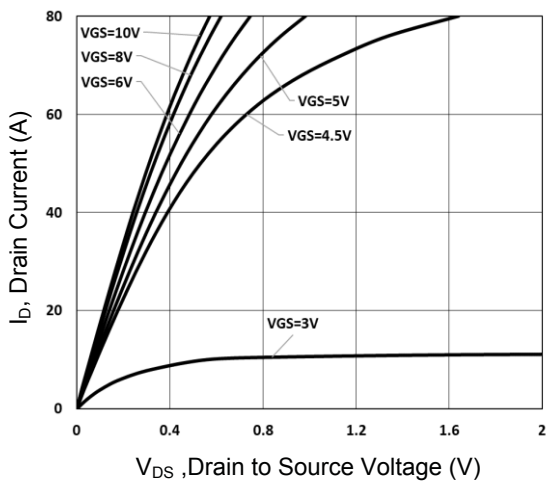


Figure 5. Typical Output Characteristics

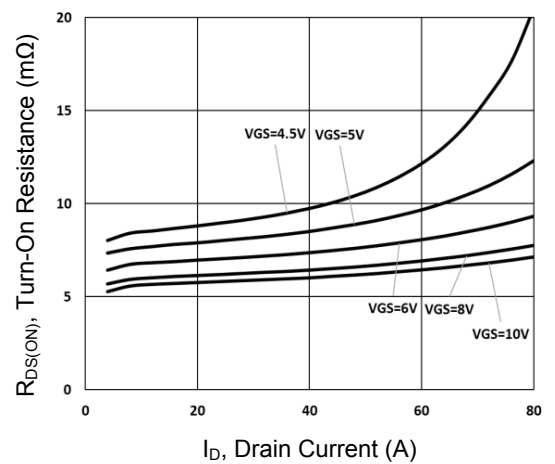


Figure 6. Turn-On Resistance vs. I_D

Typical Electrical and Thermal Characteristic Curves

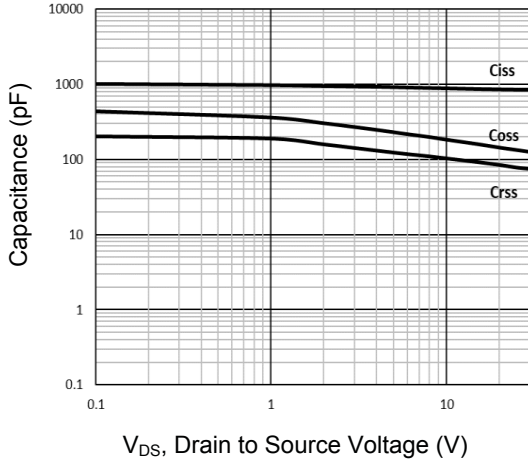


Figure 7. Capacitance Characteristics

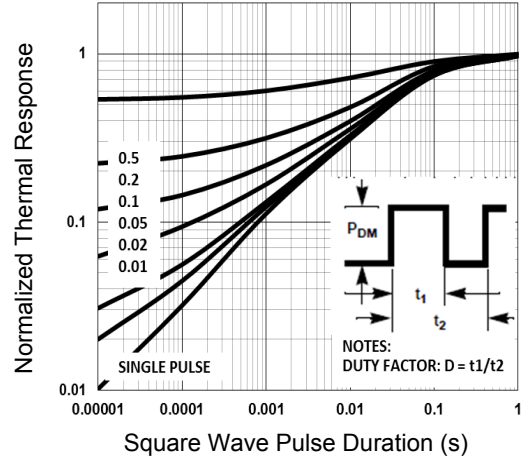


Figure 8. Normalized Transient Impedance

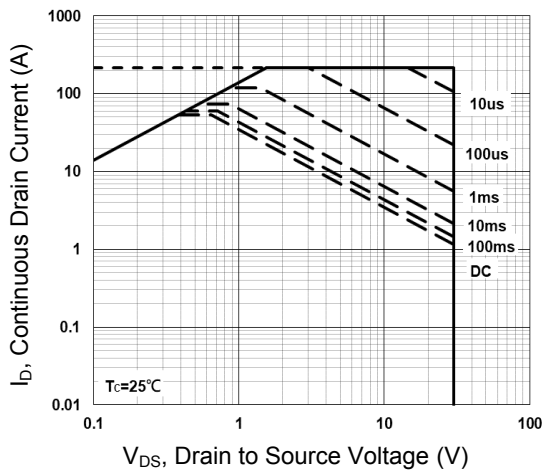


Figure 9. Maximum Safe Operation Area

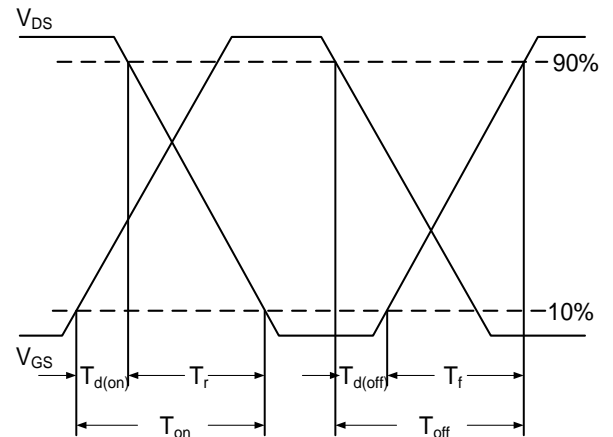


Figure 10. Switching Time Waveform

$$EAS = \frac{1}{2} L \times I_{AS}^2 \times \frac{BV_{DSS}}{BV_{DSS} - V_{DD}}$$

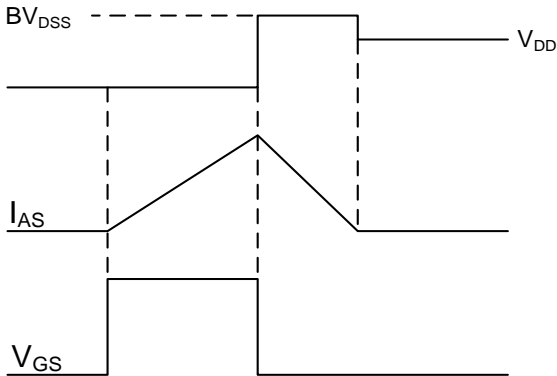
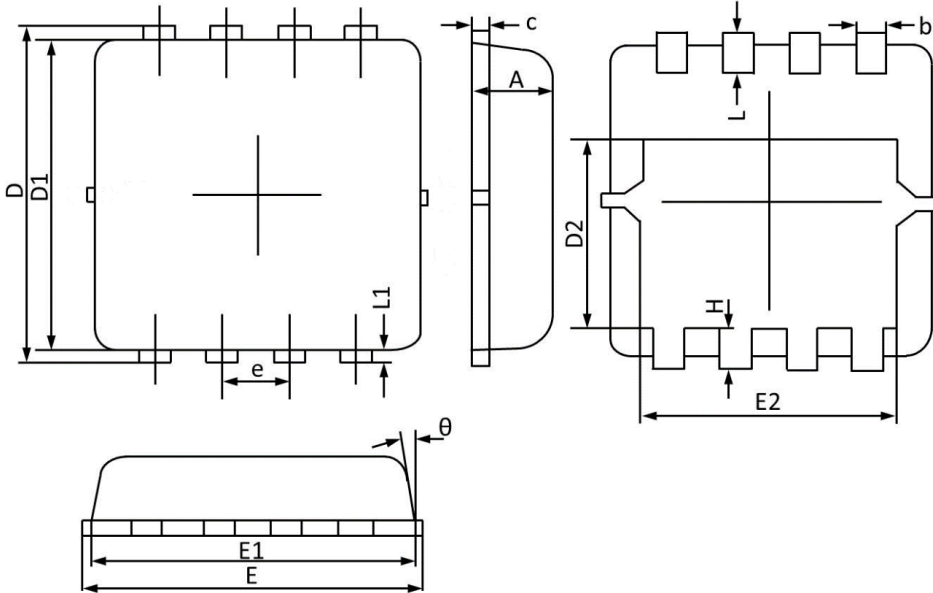


Figure 11. EAS Waveform

Package Outline Dimensions (PPAK3x3)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.700	0.900	0.028	0.035
b	0.250	0.350	0.010	0.014
c	0.100	0.250	0.004	0.010
D	3.050	3.500	0.120	0.138
D1	2.900	3.200	0.114	0.126
D2	1.350	1.950	0.053	0.077
E	3.000	3.400	0.118	0.134
E1	2.900	3.300	0.114	0.130
E2	2.350	2.600	0.093	0.102
e	0.65BSC		0.026BSC	
H	0.300	0.750	0.012	0.030
L	0.300	0.600	0.012	0.024
L1	0.060	0.200	0.002	0.008
θ	6°	14°	6°	14°